

US-PAT-NO: 6168836

DOCUMENT-IDENTIFIER: US 6168836 B1

TITLE: Process for plating upon a polymeric surface

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Alternatively the composition which comprises the polymeric surface may comprise only one pre-polymer or type of pre-polymer and one crosslinking agent or type of crosslinking agent. In this case the composition would merely be subjected to heat and/or radiation, as applicable, to an extent such that the composition is only partially cured. Care must be taken to insure consistency in the amount of cure or polymerization prior to plating. The composition is then plated upon and subsequently further cured.

The process requires that the polymeric surface be only partially polymerized or cured when plated. The inventors have found that it is preferable for the polymeric surface to be partially cured prior to plating to an extent such that 90-98 percent of the aggregate potential polymerization has occurred prior to plating. As used herein "aggregate potential polymerization" refers to the actual total degree of polymerization which is achievable with any particular composition in practice (as measured by the glass transition point of the material or some other appropriate method such as differential scanning calorimetry) not necessarily the theoretical potential.